3rd Generation Intel® Core™ Processor Embedded Controller Rugged Conduction-Cooled



APPLICATIONS

The VP 91x/x1x-RC is a PC-compatible high performance, high functionality, ruggedized conduction-cooled VME processor board supporting the 3rd generation Intel® Core™ processors and the Mobile Intel® QM77 Express Chipset with up to 16 Gbytes of DDR3-1600 ECC DRAM. This single slot board features 2 PMC/XMC sites and a variety of interfaces including an

option for an on-board mass storage and CompactFlash® site. The VP 91x/x1x is suitable for a range of demanding applications within the defense, industrial control, telecomms, telemetry, scientific and aerospace markets. To simplify the board's integration many popular industry standard operating systems are supported.

HIGHLIGHTS

- Ruggedized 6U single board computer:
 - conduction-cooled to IEEE 1101.2
 - removable front rib (VITA 20)
 - supports 2 conduction-cooled PMC or XMC modules conforming to ANSI/VITA 20
 - -40°C to +85°C operating temperature (at card edge)
 - conformally coated
- 3rd generation Intel® Core™ processor:
 - 4-core 2.1 GHz Intel Core i7-3612QE processor
 - 2-core 2.5 GHz Intel Core i7-3555LE processor
 - 2-core 1.7 GHz Intel Core i7-3517UE processor
- Up to 16 Gbytes of DDR3-1600 DRAM with ECC
- Up to 3 x external SATA interfaces plus optional on-board Solid State Flash Disk
- Onboard CompactFlash® site
- 2 x PMC/XMC module interfaces with rear I/0:
 - 32/64-bit, 33/66/100 MHz PCI/PCI-X™
 - 2 x XMC module interfaces (x8 PCI Express®)
- 2 x 10/100/1000 Mbps Ethernet interfaces, with optional Gigabit Ethernet for VME64x backplane (VITA 31.1)
- 2 x serial channels, and up to 2 x USB interfaces
- VGA graphics, DVI-D and optional DVI-I graphics interfaces

- Keyboard and mouse interfaces
- VME-64 Interface (factory build option):
 - A32/A24/A16/D64/D32/D16/D8(E0), MBLT64
 - support for fast hardware byte-swapping
- 8 Mbytes of BIOS Flash EPROM, dual devices
- 64 Mbytes of Application Flash EPROM
- Watchdog timer; Long Duration Timer
- Air-cooled versions (N, E, K-Series and RA-Series):
 - N: 0°C to +55°C, commercial, non-ruggedized
 - E: -25°C to +75°C, extended, non-ruggedized
 - K: -40°C to +85°C, humidity-sealed, non-ruggedized
 - RA: -40°C to +75°C, conformally coated, ruggedized
- Optional support for:
 - Built-In Test (BIT) firmware and software
 - Board-level security package
 - Trusted Platform Module (TPM)
- Support for Linux®, Windows®, VXWorks® QNX®, Solaris™ and LynxOS®
- Rear plug compatibility with the popular
 VP 717/08x-RC and VP 417/03x-RC families



Specification

Ruggedized dual PMC/XMC controller

- conduction-cooled to IEEE 1101.2
- supports 2 x conduction-cooled PMC or XMC modules conforming to ANSI/VITA 20
- conformally coated
- ruggedized and commercial air-cooled versions, see separate datasheets:
 - → rear plug compatible
 - → rugged air-cooled: VP 91x/x1x-RA
 - → commercial air-cooled: VP 91x/x1x

Central Processor

- 3rd generation Intel[®] Core[™] processors:
 - → 4-core 2.1 GHz Intel Core i7-3612QE processor
 - → 2-core 2.5 GHz Intel Core i7-3555LE processor
 - → 2-core 1.7 GHz Intel Core i7-3517UE processor
 - → up to 4 Mbytes of shared Last-Level cache
- utilizes Mobile Intel® QM77 Express Chipset

- up to 16 Gbytes soldered DDR3-1600 ECC DRAM:
 - → single bit error correction
 - → peak bandwidth of 25 Gbytes/s
 - → dual channel architecture
- accessible from processor or VME bus

Mass Storage Interfaces

- up to 3 x external SATA interfaces:
 - → optionally 2 x SATA via P2
- → optionally 1 x SATA via PO (see Note 1)
- 1 x EIDE interface supports on-board CompactFlash® socket via SATA converter
- optional on-board 2.5-inch SATA600 mass

Ethernet Interfaces

- two Gigabit Ethernet interfaces via rear panel:
 - → accessed via optional PO (see Note 1)
 - → implemented by Intel® 82580DB LAN Controller via x2 PCI Express® Gen2 link
- support for VITA 31.1:
 - → Gigabit Ethernet for VME64x backplanes

PMC/XMC Interfaces

- 2 x PMC shared sites supporting:
 - → 32/64-bit, 33/66/100 MHz PCI/PCI-X
- → 3.3V or 5V PCI signaling
- 2 x XMC (Switched Mezzanine Card) sites supporting:
 - → up to x8 PCI Express port
 - → XMC sites powered from 5V supply
- PMC/XMC Site 1 I/O via P2:
 - → P14 rear I/O via P2 or factory build option for reduced P14 I/O plus DVI-I graphics via P2
- PMC/XMC Site 2 I/O via optional PO:
 - → rear I/O via P24 to optional P0 includes factory build I/O options with PO (see Note 1)
- XMC Pn6 rear I/O (P16 and P26) not connected

Serial Interfaces

- 2 x serial channel interfaces:
 - 2 x RS232/422/485 accessed via P2
- 16550 compatible UARTs

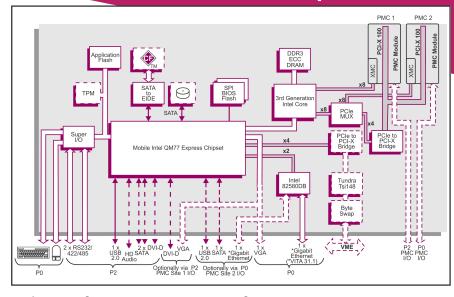
Note 1:

The optional PO connector supports either

1) PMC Site 2 P24 I/O x64 and 1 x Ethernet or

2) PMC Site 2 P24 I/O x32, SATA, USB

and 2 x Ethernet



Graphics Interfaces

- implemented by the integrated chipset graphics controller
- optional DVI-D interface via P2:
 - → digital, up to 1920 x 1080
- analog VGA interface via P2 or P0:
 - → analog, up to 1920 x 1200
- optional DVI-I interface via P2:
 - → digital, up to 1920 x 1080
 - → analog, using VGA, up to 1920 x 1200
 - → this option uses I/O pins from PMC Site 1
- all interfaces support 32-bit color depth
- support for Microsoft® DirectX 10, OpenGL 2.0, Windows® and Linux®

Other Peripheral Interfaces

- PC-compatible Real Time Clock
- up to 2 x USB 2.0 interfaces:
 - → 1 x USB via P2 connector
 - → option for USB via PO (see Note 1)
- keyboard and mouse interfaces accessed via optional PO connector
- watchdog timer
- 1 x 32-bit Long Duration Timer with processor interrupt capability

- dual 8 Mbytes of BIOS SPI Flash EPROM
- 64 Mbytes of Application Flash EPROM

Software Support

support for Linux®, Windows®, VxWorks®, QNX®, Solaris™ and LynxOS®

Optional Built-In Test (BIT) Support

Power-on BIT (PBIT), Initiated BIT (IBIT), Continuous BIT (CBIT)

Optional Board Security Packages

- Trusted Platform Module (TPM)
- proprietary board-level security features

Firmware Support

- Insyde® Software InsydeH20™ BIOS:
- → includes Compatibility Support Module based upon Intel® Platform Innovation
- Framework for EFI comprehensive Power-On Self-Test (POST)
- LAN boot firmware included

PCB (PWB) manufactured with flammability rating of ÚL94V-0

VME Interface

- P1 and P2 connectors compatible with VME64x with IDT® TSi148™ VME Bridge (build option):
 - → VME Master/Slave
 - → A32/A24/A16/D64/D32/D16/D8(E0)/MBLT64
 - → fast hardware byte swapping
 - → auto system controller detect
 - → full interrupter / interrupt handler support
 - → bus error interrupt hardware
- or without VME Bridge (build option):
 - → consult Technical Reference Manual

Electrical Specification

- +5V @ 6.5A (typical with 2.5 GHz Intel Core i7-3555LE processor and 8 Gbytes DRAM)
- +12V @ 0.0A; -12V @ 0.0A; 3.3V not required
- +12V and -12V routed to both PMC/XMC sites

Environmental Specification

- operating temperature (at card edge):
- → VITA 47 Class CC4, -40°C to +85°C
- conduction-cooled
- storage temperature:
- → VITA 47 Class C4, -55°C to +105°C
- operating altitude:
 - → -1,000 to 50,000 feet (-305 to 15,240 meters)
- 5% to 95% Relative Humidity, non condensing (operating/storage)

Mechanical Specification

- 6U form-factor
- single slot, width 0.8 inch (20.3mm)
- utilizes 160-way connectors for P1 and P2
- optional PO
- removable front rib (VITA 20)
- operating mechanical:-
- → shock VITA 47 Class OS2, 40g
- random vibration VITA 47 Class V3, 0.1q2/Hz displacement
- plug compatibility with the popular VP 717/08x-RC and VP 417/03x-RC families:
 - → only applies to VME Bridge build option

ORDERING INFORMATION

Product Description (Hardware) Order Number

For the order number suffix (yz) options please contact your local sales office: Where y = P2 and P0 I/0 configurations Where z = DRAM size

VP 91x/x1x-yzRC 3rd generation Intel Core i7 SBC (RC-Series)

y - P2 and P0 I/O configurations

z - up to 16 Gbytes DRAM